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IYODA et al.(10) **Pub. No.: US 2022/0377883 A1**(43) **Pub. Date: Nov. 24, 2022**(54) **PRINTED WIRING BOARD**(71) Applicant: **IBIDEN CO., LTD.**, Ogaki (JP)(72) Inventors: **Shigeto IYODA**, Ogaki (JP);
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(57)

ABSTRACT

A printed wiring board includes resin insulating layers, and conductor layers including a conductor layer such that the conductor layer includes a conductor circuit and that the conductor circuit has a surface index X/Y in a range of 1.00 to 2.20 where X is a length of an outer circumference of cross section of the conductor circuit, and Y is a length of an outer circumference of a reference quadrangle in the cross section of the conductor circuit. The reference quadrangle has a first reference line drawn with reference to bottom of deepest recess on first side, a second reference line is drawn with reference to bottom of deepest recess on second side, a third reference line is drawn with reference to bottom of deepest recess on third side, and a fourth reference line is drawn with reference to bottom of deepest recess on fourth side of the outer circumference.

